

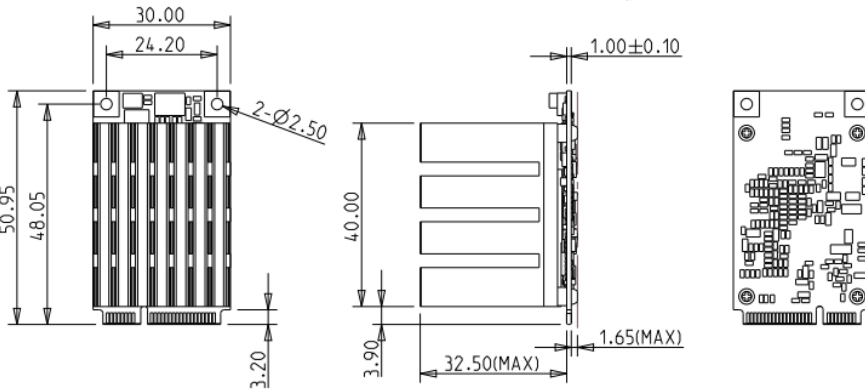
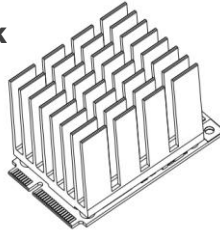


Features

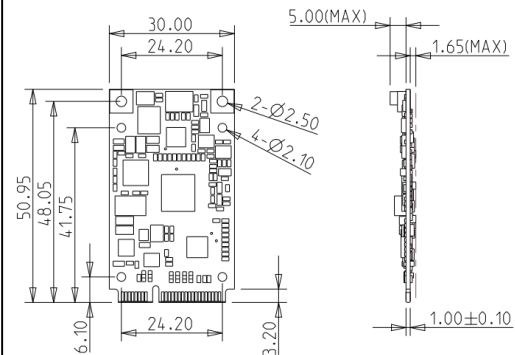
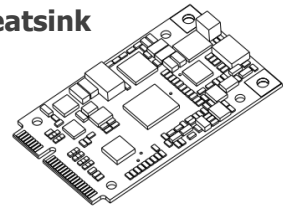
- mPCIe to 1 Movidius Myriad X
- Low Power Design
- Support Intel OpenVINO™ Toolkit
- Supported Framework: TensorFlow, Caffe, MXNET
- Complies with CE/FCC Class A
- 30μ" golden finger, 3-year warranty

Mechanical Drawing

With Heatsink



Without Heatsink



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Specifications

Form-Factor	mPCIe
Input I/F	PCI Express 2.0 x 1
TDP	4W
Dimension (WxLxH)	With Heatsink: 30 x 50.9 x 35.15 mm, Weight: 29.47g Without Heatsink: 30 x 50.9 x 7.65 mm, Weight: 6.25g
Temperature	Operation: 0°C ~ +60°C
Support Framework	TensorFlow, Caffe, MXNET
OS Support	Windows 10 64-bit Ubuntu 18.04, 64-bit
Notes	Please download OpenVINO™ Toolkit from Intel website: https://docs.openvino toolkit.org/latest/index.html

Order information

EMPA-I101-C1

mPCIe to One Intel Movidius Myriad X AI module, with Heatsink